

## Automotive N-channel 40 V, 2.4 mΩ typ., 120 A STripFET™ F6 Power MOSFET in a PowerFLAT™ 5x6 dual side cooling

Datasheet - preliminary data

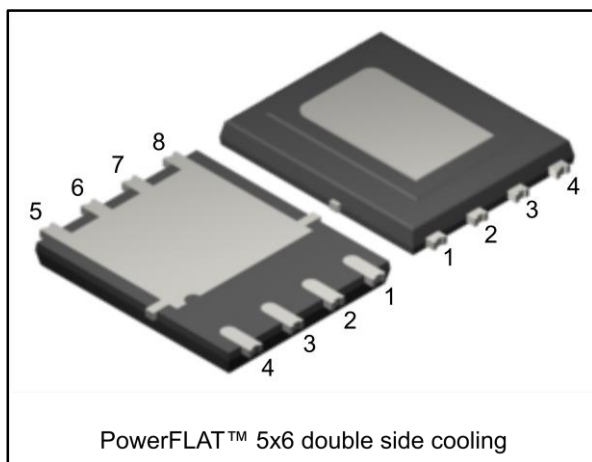
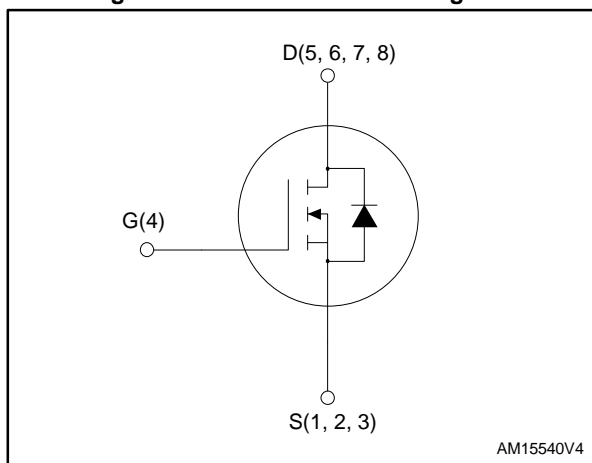


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STLD125N4F6AG	40 V	3.0 mΩ	120 A

- Designed for automotive applications
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using the STripFET™ F6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R<sub>DS(on)</sub> in all packages.

Table 1: Device summary

Order code	Marking	Package	Packaging
STLD125N4F6AG	125	PowerFLAT™ 5x6 dual side cooling	Tape and reel

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	40	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)(2)}$	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	120	A
$I_D^{(2)}$	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	101	A
$I_{DM}^{(2)(3)}$	Drain current (pulsed)	480	A
$P_{TOT}^{(2)}$	Total dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	130	W
$T_J$	Operating junction temperature range	- 55 to 175	$^{\circ}\text{C}$
$T_{stg}$	Storage temperature range		

**Notes:**<sup>(1)</sup>Limited by package.<sup>(2)</sup>The value is rated according to  $R_{thj-c}$  bottom side.<sup>(3)</sup>Pulse width limited by safe operating area.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-c}$ top side	Thermal resistance junction-case top side	2.9	$^{\circ}\text{C/W}$
$R_{thj-c}$ bottom side	Thermal resistance junction-case bottom side	1.14	
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	31.3	

**Notes:**<sup>(1)</sup>When mounted on 1 inch<sup>2</sup> 2 Oz. Cu board,  $t \leq 10\text{ s}$ 

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AV}$	Avalanche current, repetitive or not repetitive (pulse width limited by maximum junction temperature)	90	A
$E_{AS}$	Single pulse avalanche energy ( $T_J = 25\text{ }^{\circ}\text{C}$ , $I_C = I_{AV}$ , $V_{DD} = 16\text{ V}$ )	150	mJ

## 2 Electrical characteristics

(T<sub>C</sub> = 25 °C unless otherwise specified)

Table 5: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	40			V
I <sub>DSS</sub>	Zero gate voltage Drain current	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 16 V			1	μA
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 16 V, T <sub>j</sub> = 125 °C <sup>(1)</sup>			10	μA
I <sub>GSS</sub>	Gate-body leakage current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1 mA	2		4	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A		2.4	3	mΩ
		V <sub>GS</sub> = 6.5 V, I <sub>D</sub> = 75 A		2.7	3.5	

**Notes:**

<sup>(1)</sup>Defined by design. Not subject to production test.

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 10 V, f = 1 MHz, V <sub>GS</sub> = 0 V	-	5600	-	pF
C <sub>oss</sub>	Output capacitance		-	890	-	pF
C <sub>rss</sub>	Reverse transfer capacitance		-	560	-	pF
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 32 V, I <sub>D</sub> = 75 A, V <sub>GS</sub> = 10 V (see <a href="#">Figure 14: "Test circuit for gate charge behavior"</a> )	-	91	-	nC
Q <sub>gs</sub>	Gate-source charge		-	28	-	nC
Q <sub>gd</sub>	Gate-drain charge		-	27	-	nC

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 75 A R <sub>G</sub> = 30 Ω, V <sub>GS</sub> = 10 V (see <a href="#">Figure 13: "Test circuit for resistive load switching times"</a> )	-	47	-	ns
t <sub>r</sub>	Rise time		-	300	-	ns
t <sub>d(off)</sub>	Turn-off-delay time		-	255	-	ns
t <sub>f</sub>	Fall time		-	220	-	ns

Table 8: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)}$	Source-drain current		-		120	A
$I_{SDM}^{(1)(2)}$	Source-drain current (pulsed)		-		480	A
$V_{SD}^{(3)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 90\text{ A}$	-		1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 90\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 20\text{ V}$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> )	-	40		ns
$Q_{rr}$	Reverse recovery charge		-	41		nC
$I_{RRM}$	Reverse recovery current		-	2		A

**Notes:**<sup>(1)</sup>Limited by package.<sup>(2)</sup>Pulse width is limited by safe operating area<sup>(3)</sup>Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

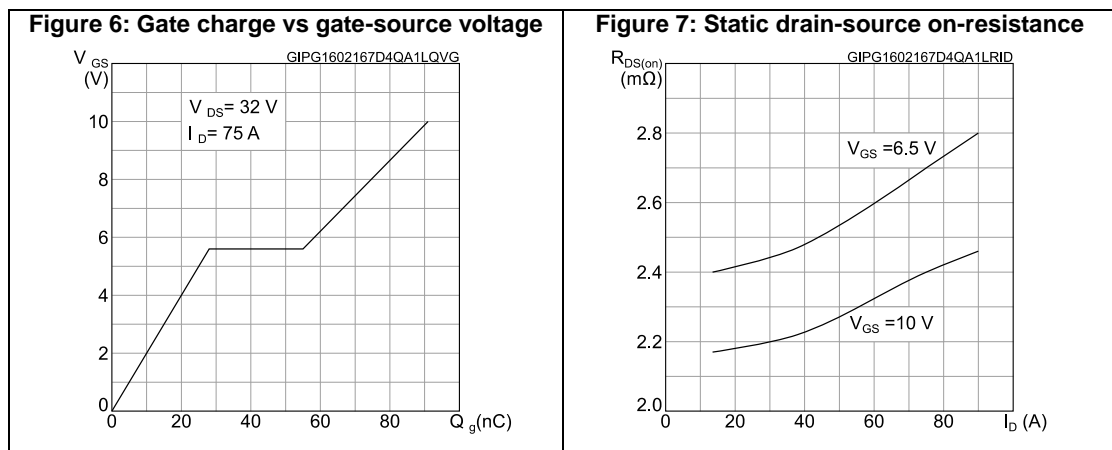
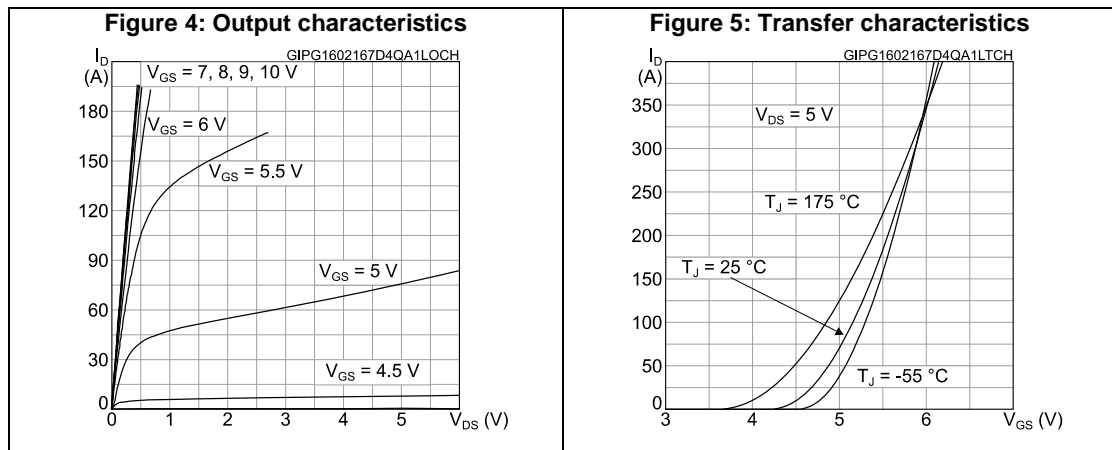
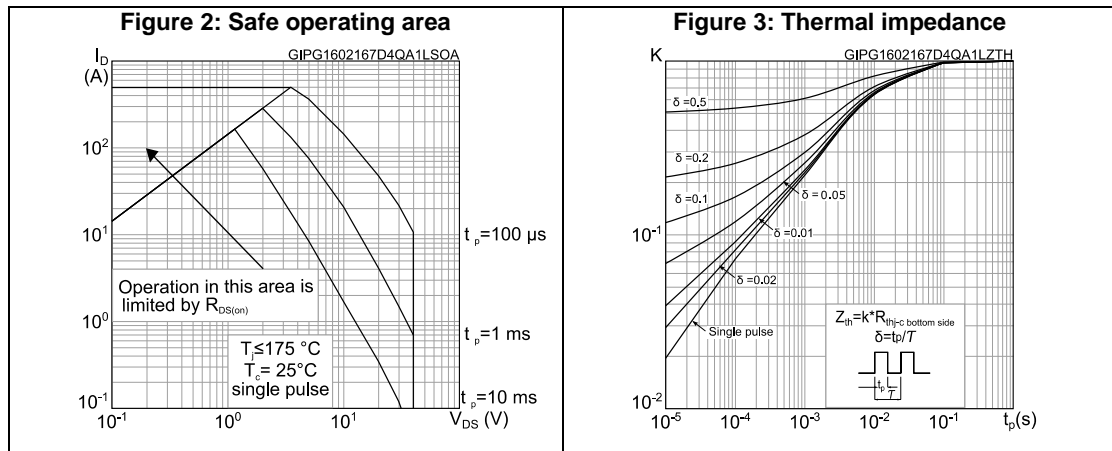


Figure 8: Capacitance variations

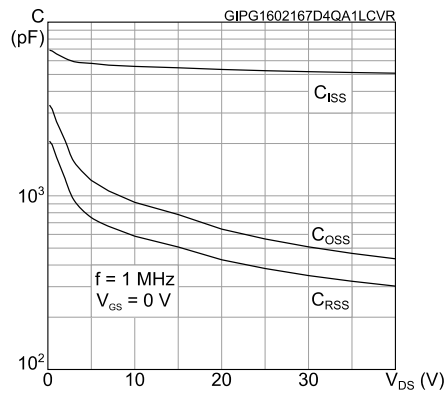


Figure 9: Normalized gate threshold voltage vs temperature

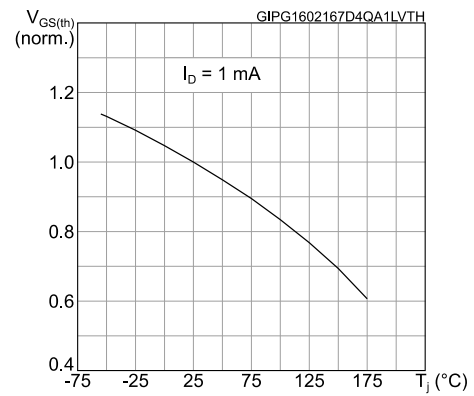


Figure 10: Normalized on-resistance vs temperature

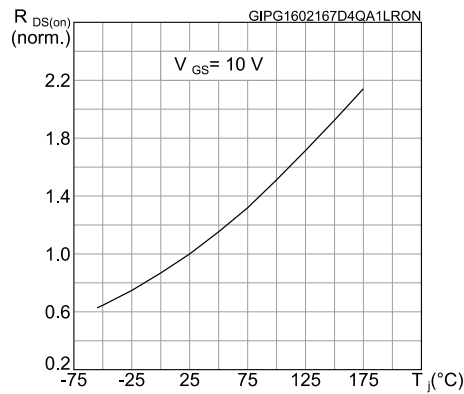


Figure 11: Normalized V(BR)DSS vs temperature

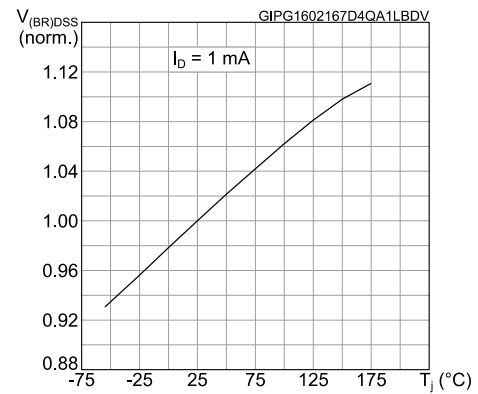
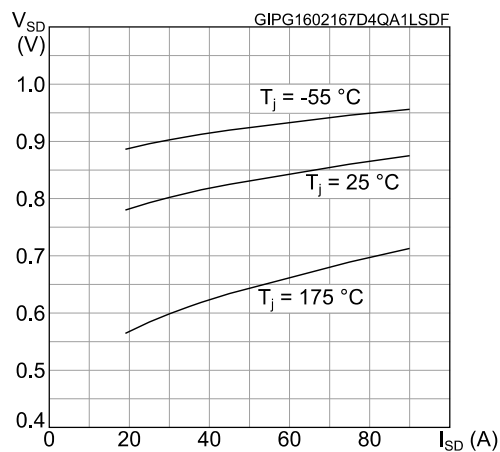
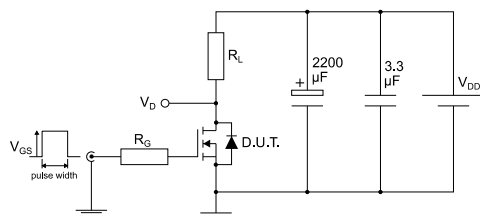


Figure 12: Source-drain diode forward characteristics



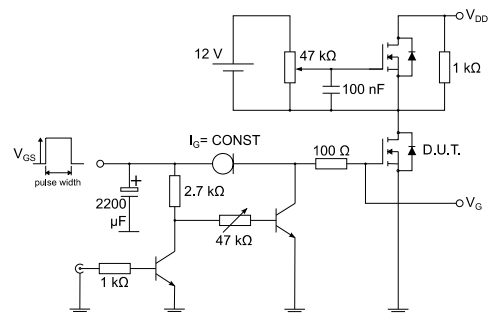
### 3 Test circuits

**Figure 13: Test circuit for resistive load switching times**



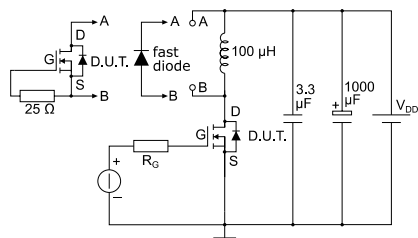
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**Figure 14: Test circuit for gate charge behavior**



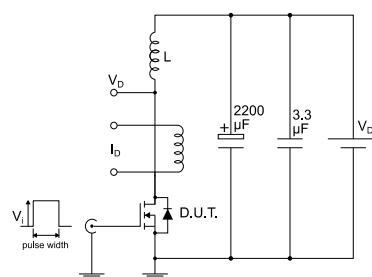
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**Figure 15: Test circuit for inductive load switching and diode recovery times**



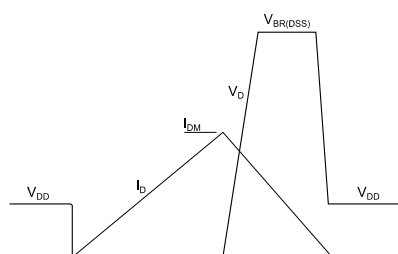
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**Figure 16: Unclamped inductive load test circuit**



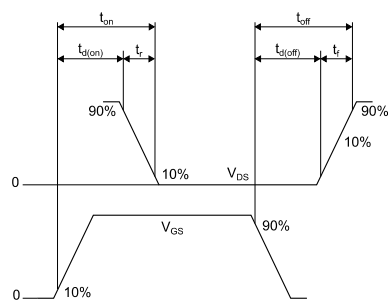
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**Figure 17: Unclamped inductive waveform**



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**Figure 18: Switching time waveform**



AM01473v1



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 PowerFLAT™ 5X6 dual side cooling package information

Figure 19: PowerFLAT™ 5x6 dual side cooling package outline

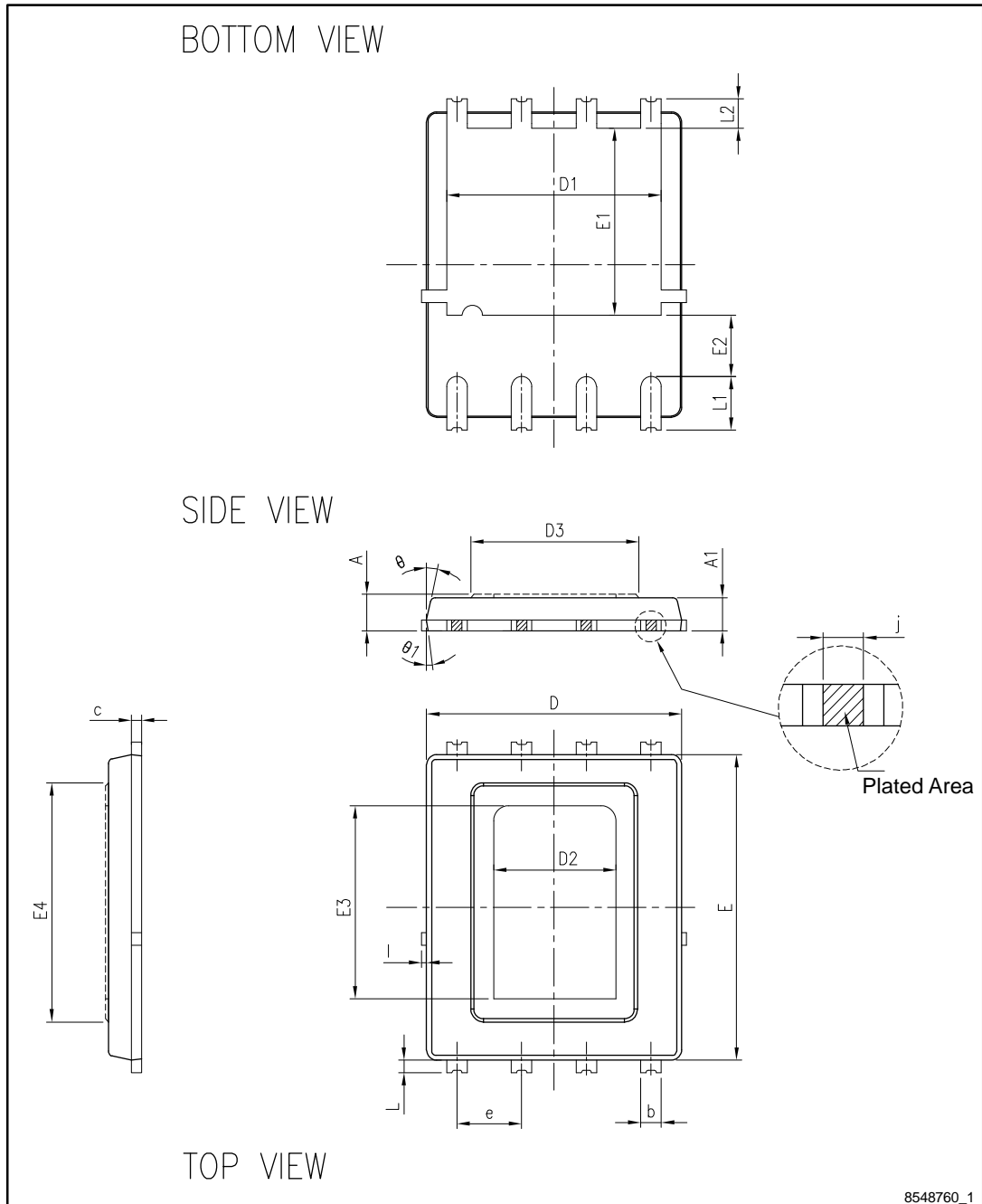
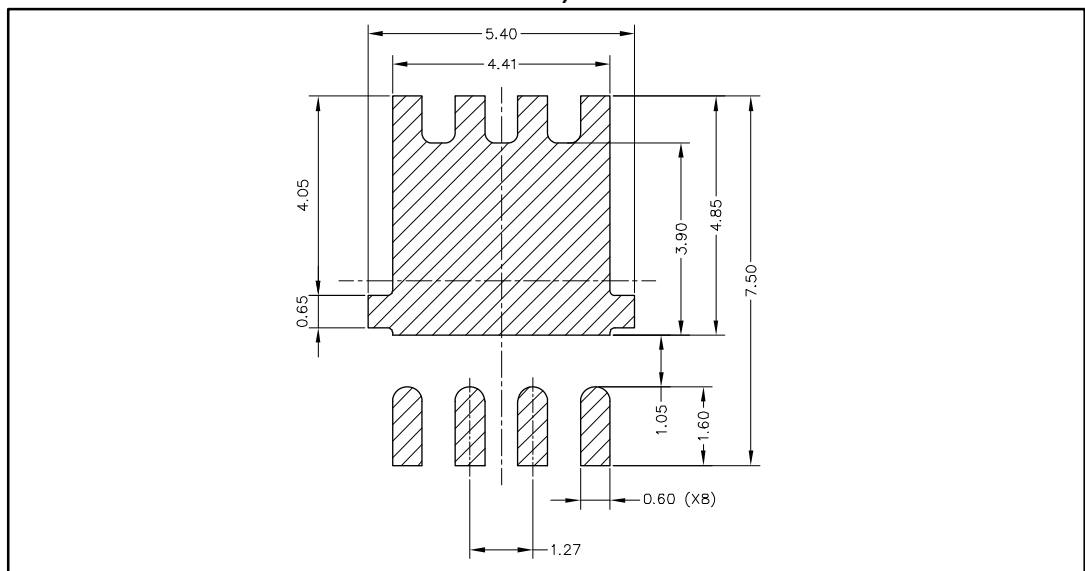


Table 9: PowerFLAT™ 5x6 dual side cooling mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.66	0.71	0.76
A1	0.60		0.75
b	0.33	0.43	0.53
c	0.15	0.203	0.30
D	5.00 BSC		
D1	4.06	4.21	4.36
D2	2.40 BSC		
D3	2.80	3.30	3.80
E	6.00 BSC		
E1	3.525	3.675	3.825
E2	1.05	1.20	1.35
E3	3.80 BSC		
E4	4.20	4.70	5.20
e	1.27 BSC		
l			0.15
L	0.15	0.25	0.35
L1	0.925	1.05	1.175
L2	0.45	0.575	0.70
ϑ	12° BSC		
ϑ1	7° BSC		
j	0.20 BSC		

Figure 20: PowerFLAT™ 5x6 dual side cooling recommended footprint (dimensions are in mm)



## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
16-Feb-2016	1	First release.

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